

4-line IPAD™, ultra-large bandwidth ESD protection

Features

- 4-line 15 kV ESD protection
- Ultra low line capacitance (0.7 pF typ.)
- Ultra-large bandwidth
 - no influence on signal rise and fall times
 - maximized number of signal harmonics
- Flow-through layout with Type C HDMI™ connector
- Low PCB space occupation - 1.76 mm² footprint
- Very low leakage current: 0.1 µA max.
- 0.4 mm pitch WLCSP package to minimize parasitic inductances
- RoHS compliant

Complies with the standards:

- IEC 61000-4-2 Level 4
 - ± 15 kV (air discharge)
 - ± 8 kV (contact discharge)

Applications

- Mobile phones
- HDMI ports at 1.65 Gb/s and up to 3.2 Gb/s
- USB 2.0 ports up to 480 Mb/s (Hi-Speed)
- Video line protection

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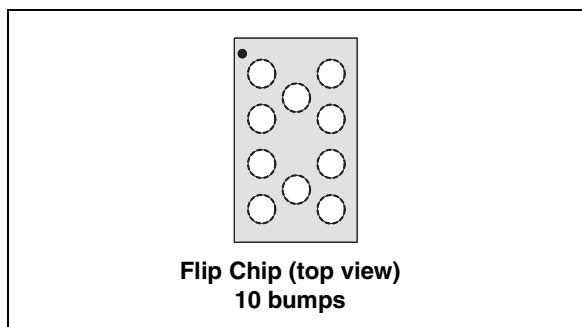
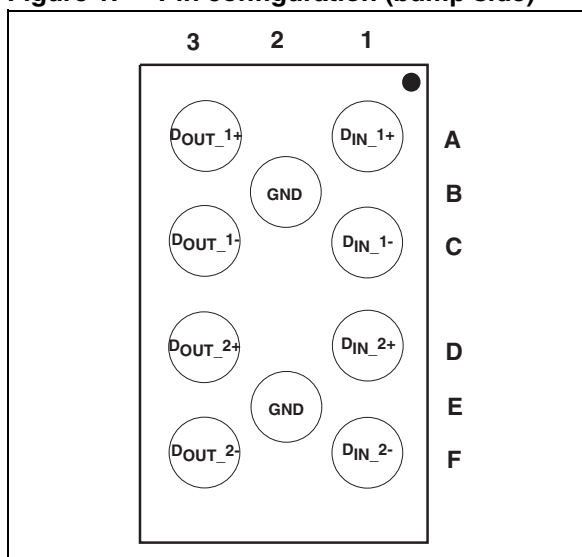


Figure 1. Pin configuration (bump side)



Description

The HDMIULC6-4F3 is a monolithic, application specific discrete device dedicated to ESD protection of the HDMI connection. It also offers the same high level of protection for IEEE 1394a and IEEE 1394b/c, USB 2.0, Ethernet links, and video lines.

Its ultra high cutoff frequency (7 GHz) secures a high level of signal integrity. The device topology provides this integrity without compromising the complete protection of ICs against the most stringent ESD strikes.

1 Characteristics

Figure 2. Internal circuit schematic (top view)

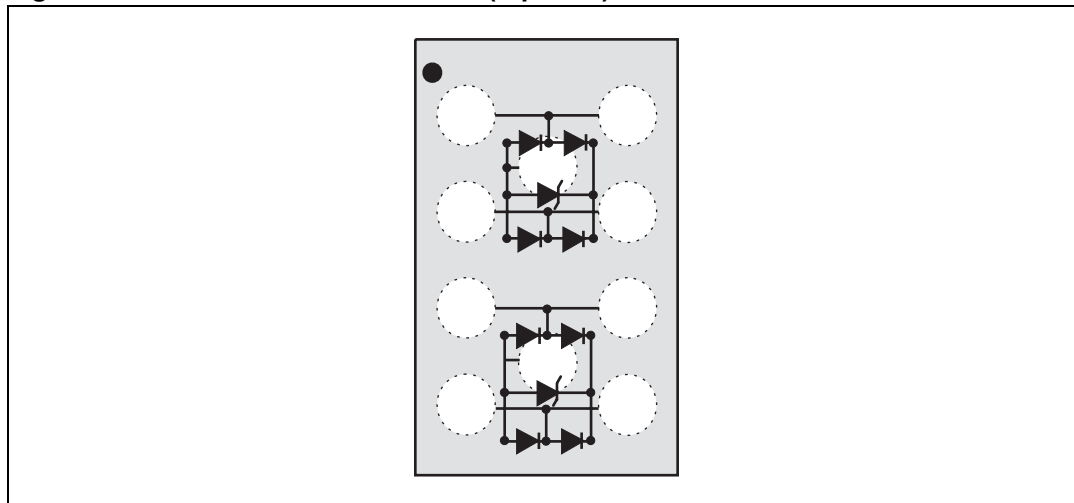


Table 1. Absolute maximum ratings ($T_{amb} = 25\text{ }^{\circ}\text{C}$)

Symbol	Parameter	Value	Unit
V_{PP}	ESD discharge IEC 61000-4-2		
	Air discharge	± 15	kV
	Contact discharge	± 15	
P_{PP}	Peak pulse power dissipation (8/20 μs)	70	W
T_j	Maximum junction temperature	125	$^{\circ}\text{C}$
T_{stg}	Storage temperature range	-55 to + 150	$^{\circ}\text{C}$

Table 2. Electrical characteristics (T_{amb} = 25 °C)

Symbol	Parameter	Test condition	Min.	Typ.	Max.	Unit
V _{BR}	Breakdown voltage between VBUS and GND	I _R = 1 mA	6		9	V
I _{RM}	Leakage current	V _{RM} = 3 V		3	100	nA
C _{I/O-GND} ⁽¹⁾	Capacitance between I/O and GND	V _{line} = 0 V, V _{osc} = 30 mV, F = 1 MHz		1.3		pF
		V _{line} = 0 V, V _{osc} = 30 mV, F = 825 MHz		0.7	0.9	pF
ΔC _{I/O-GND} ⁽¹⁾	Capacitance variation between I/O and GND	V _{line} = 0 V, V _{osc} = 30 mV, F = 1 MHz between two lines of the same lane		0.06		pF
C _{I/O-I/O}	Capacitance between I/O	V _{line} = 0 V, V _{osc} = 30 mV, F = 1 MHz		0.9		pF
		V _{line} = 0 V, V _{osc} = 30 mV, F = 825 MHz		0.55	0.65	pF
ΔC _{I/O-I/O}	Capacitance variation between I/O	V _{line} = 0 V, V _{osc} = 30 mV, F = 1 MHz		0.05		pF
BW	Bandwidth	- 3 dB		7		GHz

1. C_{I/O-GND} values are given per line and relative to one GND.

Figure 3. S21 versus frequency

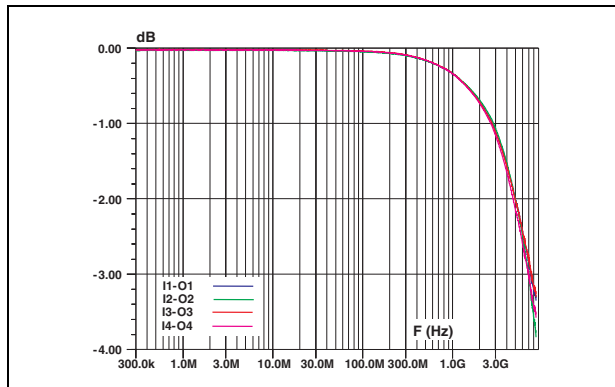


Figure 4. Analog crosstalk measurements

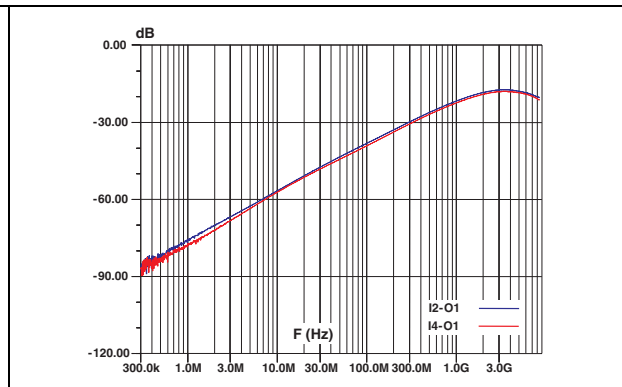


Figure 5. Digital crosstalk measurements I1 - O2

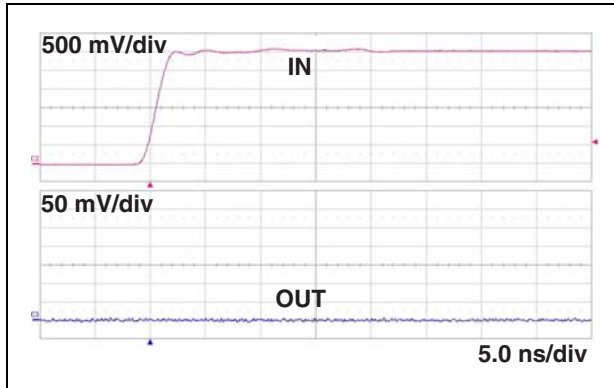


Figure 6. Digital crosstalk measurements I2 - O3

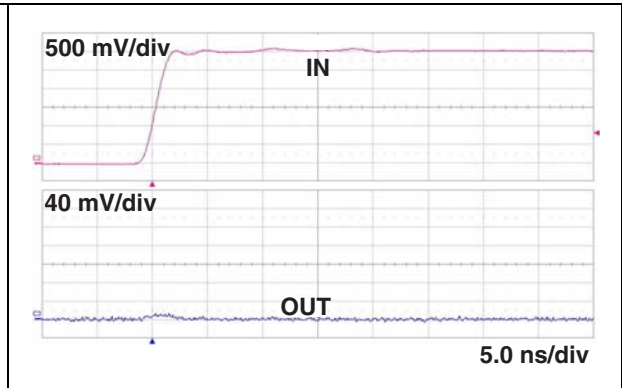


Figure 7. Step response attenuation I1 - O1

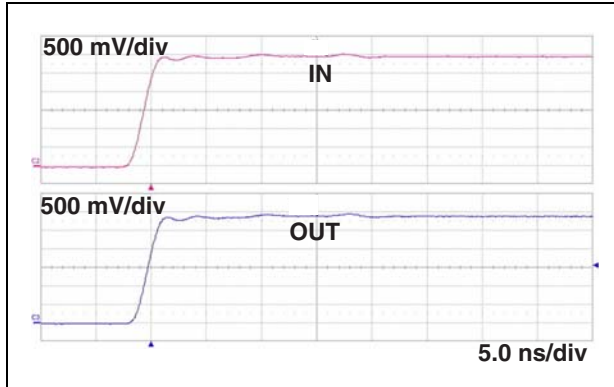


Figure 8. Step response attenuation I2 - O2



Figure 9. ESD response to IEC 61000-4-2 (+8 kV contact discharge) on I1 - O1

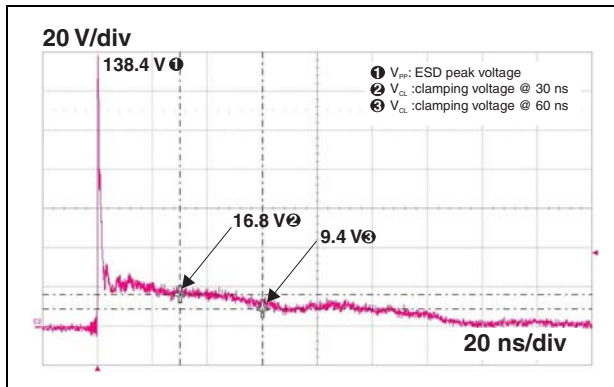


Figure 10. ESD response to IEC 61000-4-2 (-8 kV contact discharge) on I1 - O1

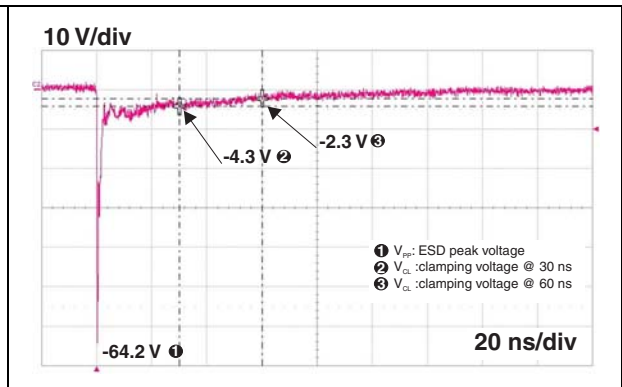


Figure 11. ESD response to IEC 61000-4-2 (+8 kV contact discharge) on I2 - O2

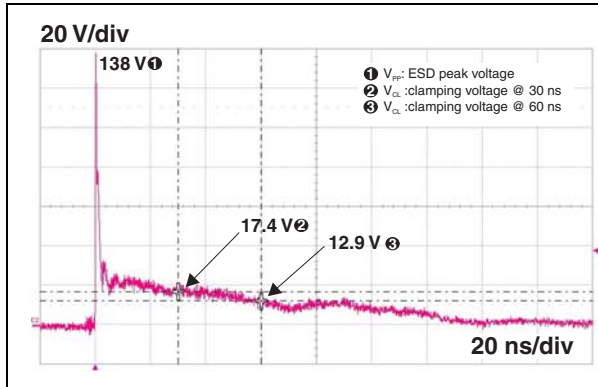


Figure 12. ESD response to IEC 61000-4-2 (-8 kV contact discharge) on I2 - O2

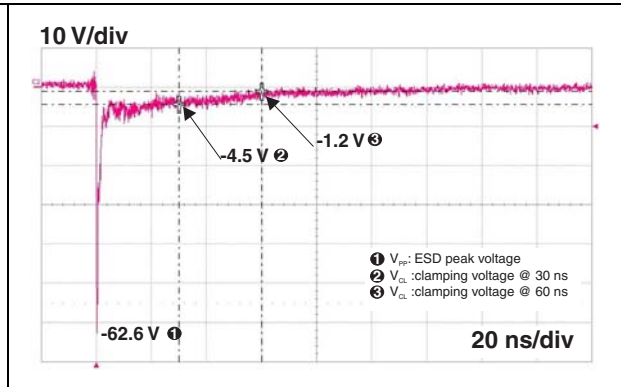


Figure 13. ESD response to IEC 61000-4-2 (+8 kV contact discharge) on I3 - O3

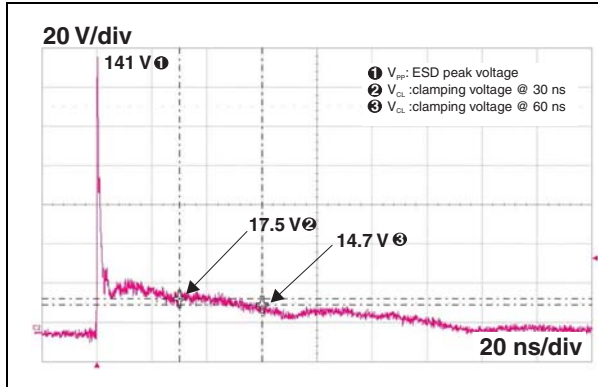


Figure 14. ESD response to IEC 61000-4-2 (-8 kV contact discharge) on I3 - O3

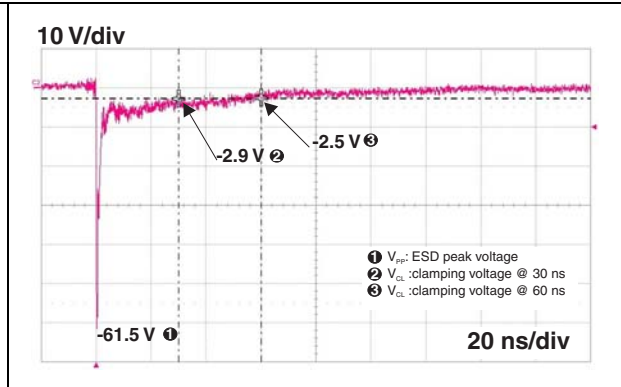
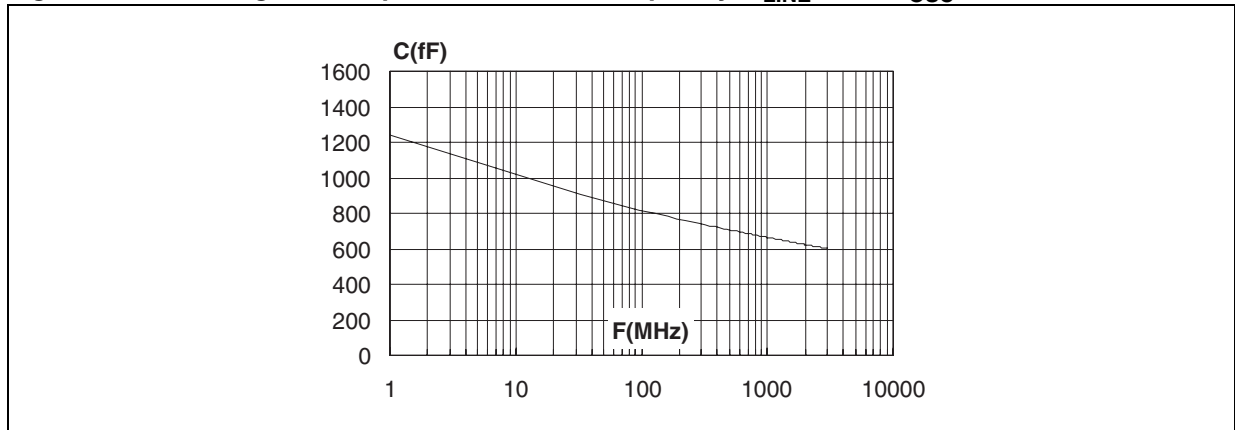
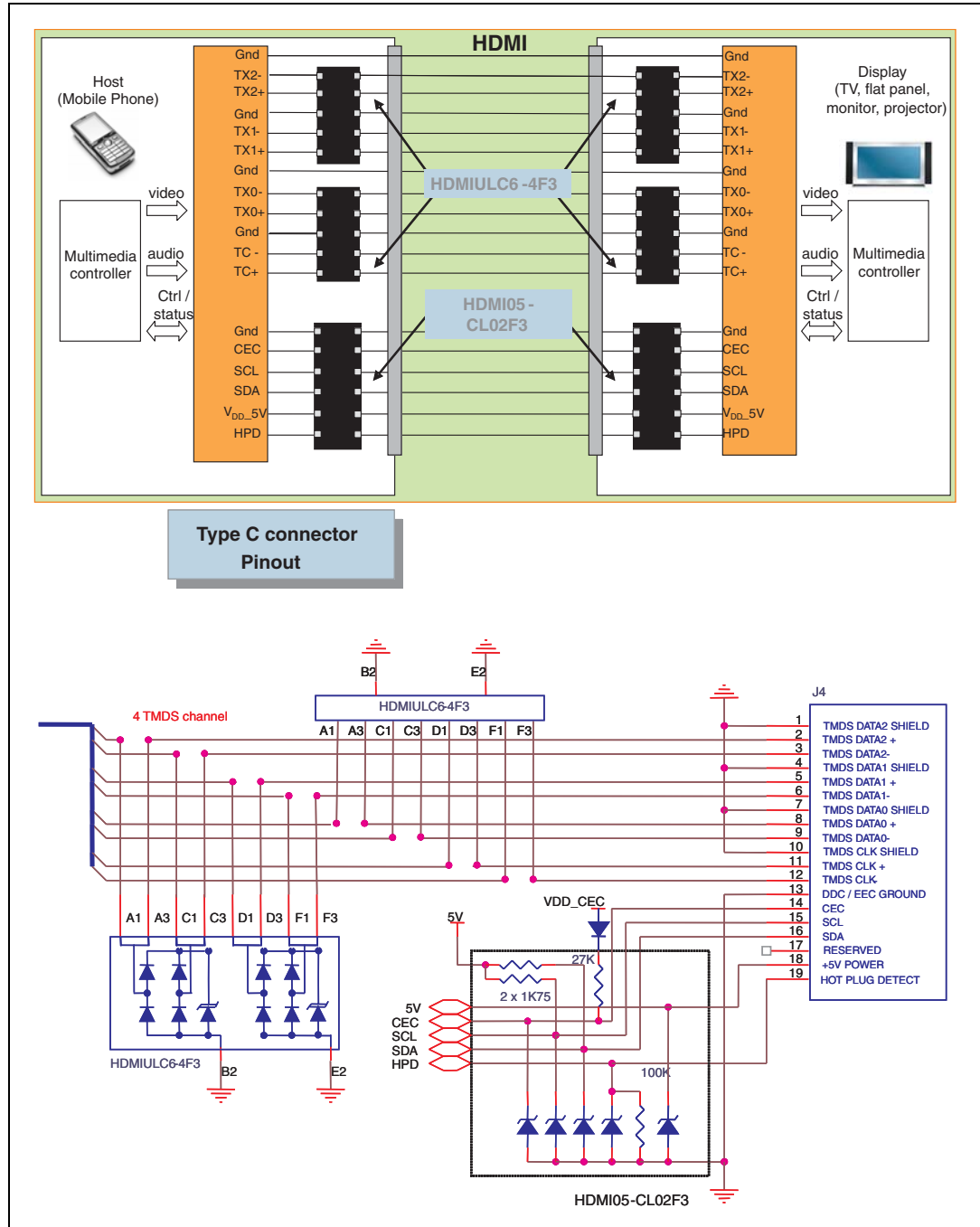


Figure 15. Line to ground capacitance versus frequency, $V_{LINE} = 0 V$, $V_{OSC} = 30 mV$



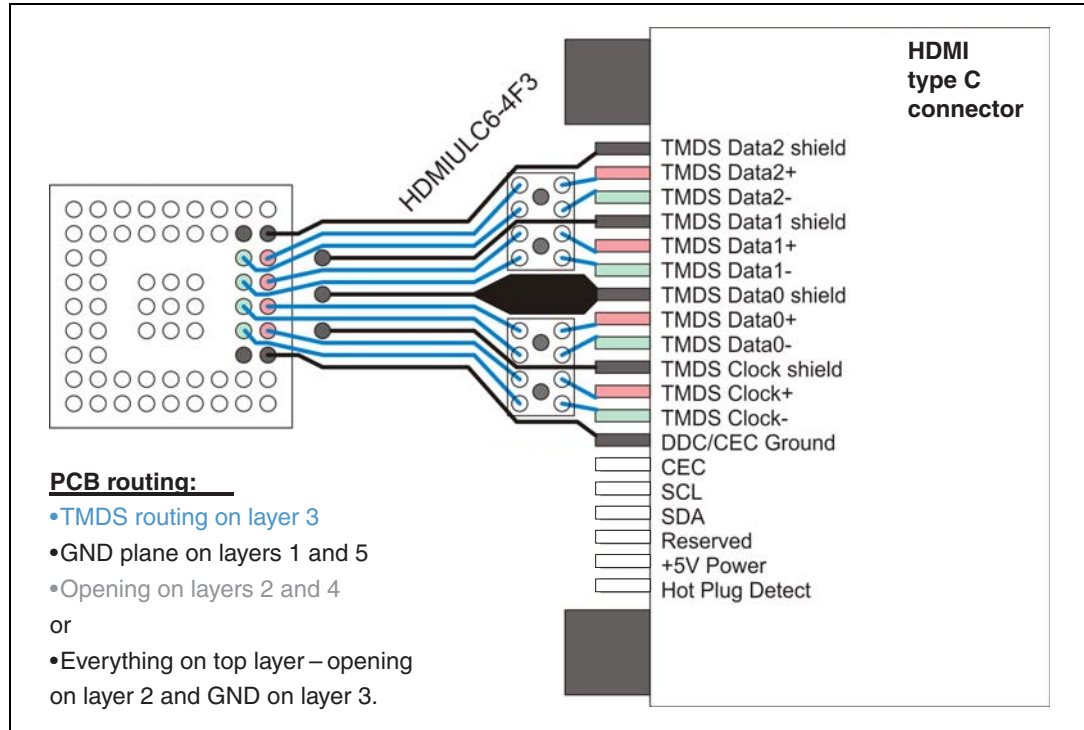
2 Typical application schematic

Figure 16. Implementation with HDMI type C connector



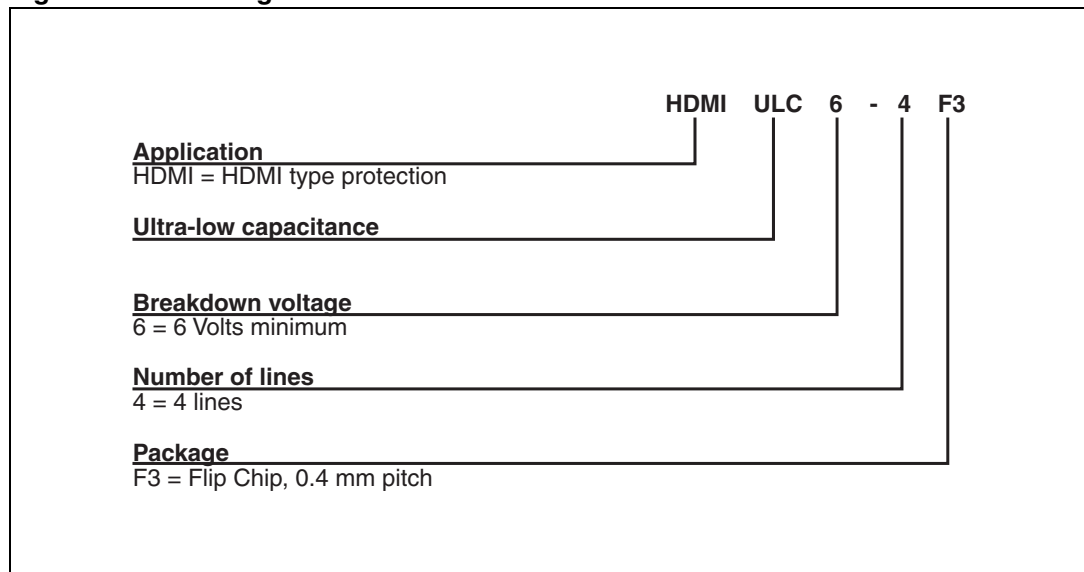
3 Layout recommendations

Figure 17. Layout recommendations



4 Ordering information scheme

Figure 18. Ordering information scheme



5 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

Figure 19. Flip Chip dimensions

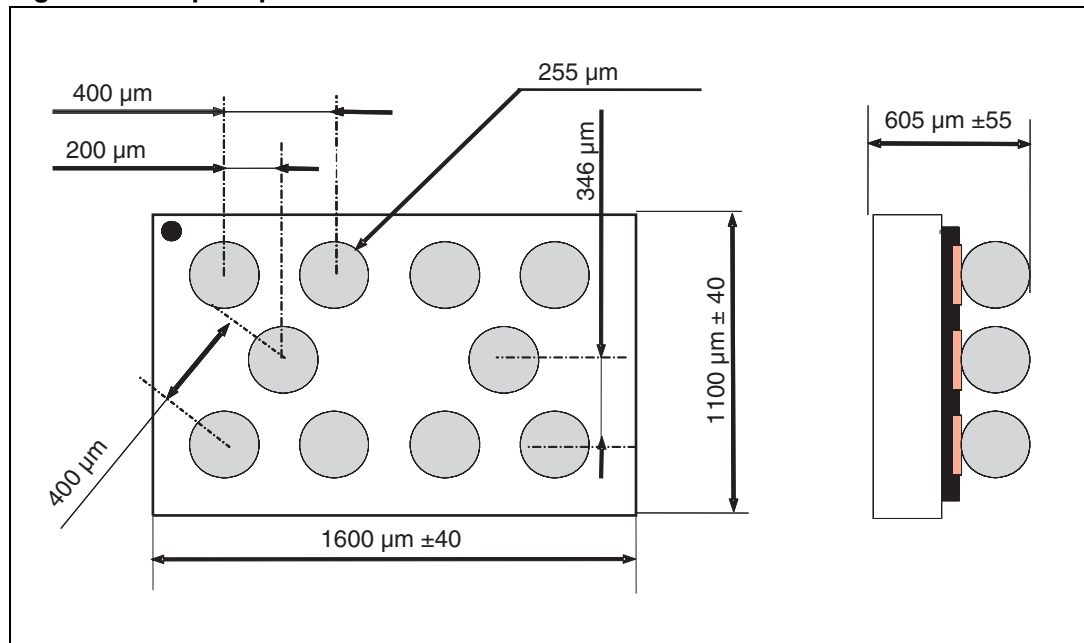


Figure 20. Footprint recommendations

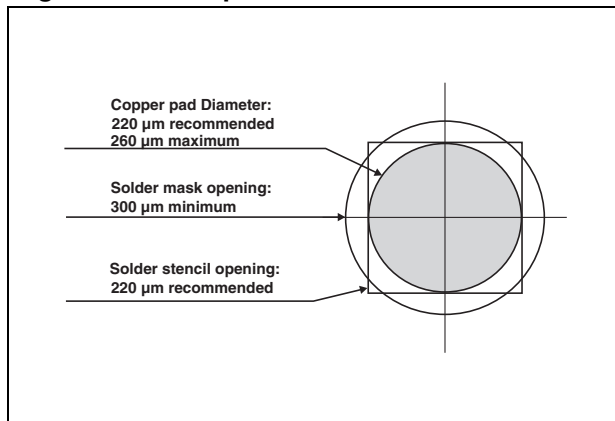


Figure 21. Marking

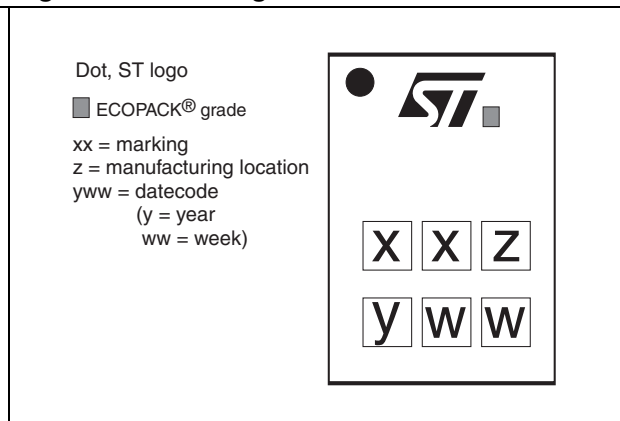
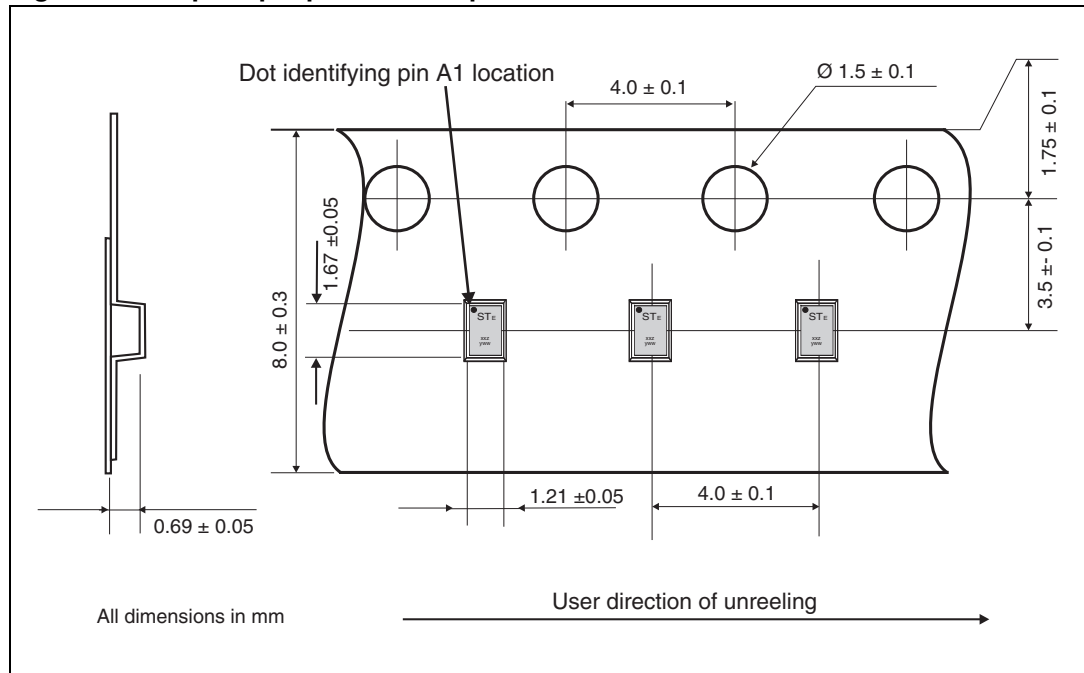


Figure 22. Flip Chip tape and reel specification



6 Ordering information

Table 3. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
HDMIULC6-4F3	EP	Flip Chip	2.6 mg	5000	Tape and reel (7")

7 Revision history

Table 4. Document revision history

Date	Revision	Changes
24-Mar-2009	1	First issue.
10-Sep-2009	2	Removed "Electrical characteristics, parameters" table. Updated Table 2 and Table 3 . Updated Figure 18 . Added dimension in Figure 19 .

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